















ESD

TVS

MOS

LDO

Diode

Sensor

DC-DC

Product Specification

| Domestic Part Number | IRF9Z24N |
|--------------------------|----------|
| Overseas Part Number | IRF9Z24N |
| ▶ Equivalent Part Number | IRF9Z24N |





-60V P-Channel Enhancement Mode MOSFET

Description

The IRF9Z24N uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

Application

Battery protection

Load switch

Uninterruptible power supply

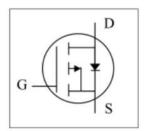
General Features

 $V_{DS} = -60V I_{D} = -20A$

 $R_{DS(ON)} < -110 \,\text{m}\Omega$ @ $V_{GS} = -10 \,\text{V}$

TO-220-3L Pin Configuration





Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

| Parameter | Symbol | Limit | Unit | |
|--|----------------------------------|------------|------|--|
| Drain-Source Voltage | V _{DS} | -60 | V | |
| Gate-Source Voltage | V _{GS} | ±20 | V | |
| Drain Current-Continuous | lo | -20 | Α | |
| Drain Current-Continuous(Tc=100 ℃) | I _D (100°C) | -16 | Α | |
| Pulsed Drain Current | Ірм | -260 | Α | |
| Maximum Power Dissipation | PD | 1.92 | W | |
| Derating factor | | 0.87 | W/°C | |
| Single pulse avalanche energy (Note 5) | Eas | 50 | mJ | |
| Operating Junction and Storage Temperature Range | T _J ,T _{STG} | -55 To 175 | °C | |
| Thermal Resistance, Junction-to-Case ^(Note 2) | Reuc | 65 | °CM | |

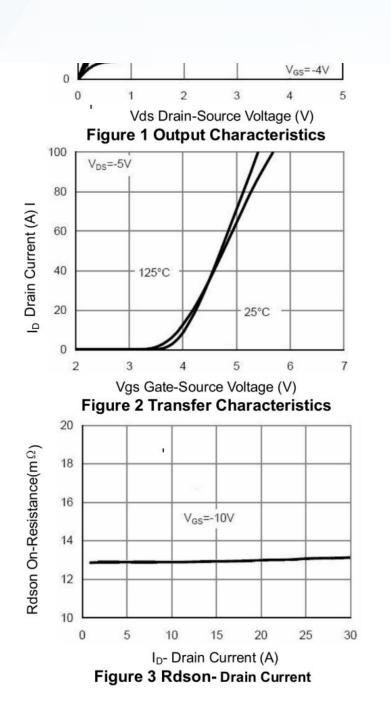


| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =-250µA | -60 | - | - | V |
|----------------------------------|---------------------|---|------|-------|------|----|
| Zero Gate Voltage Drain Current | loss | V _{DS} =-60V,V _{GS} =0V | - | - | -1 | μA |
| Gate-Body Leakage Current | Igss | V _{GS} =±20V,V _{DS} =0V | - | - | ±100 | nA |
| Gate Threshold Voltage | VGS(th) | V _{DS} =V _{GS} ,I _D =-250μA | -1.0 | -1.63 | -3.0 | ٧ |
| Drain-Source On-State Resistance | RDS(ON) | V _{GS} =-10V, I _D =-20A | 3.0 | 90 | 110 | mΩ |
| Forward Transconductance | grs | V _{DS} =-5V,I _D =-20A | - | 25 | - | S |
| Input Capacitance | Clss | V _{DS} =-25V,V _{GS} =0V, F=1.0MHz | - | 1800 | - | PF |
| Output Capacitance | Coss | | - | 420 | - | PF |
| Reverse Transfer Capacitance | Crss | | - | 145 | - | PF |
| Turn-on Delay Time | t _{d(on)} | V_{DD} =-30V, R_L =1.5 Ω , V_{GS} =-10V, R_G =3 Ω | - | 53 | - | nS |
| Turn-on Rise Time | tr | | - | 19 | - | nS |
| Turn-Off Delay Time | t _{d(off)} | | - | 221 | - | nS |
| Turn-Off Fall Time | tf | | - | 61 | - | nS |
| Total Gate Charge | Qg | V _{DS} =-30,I _D =-20A, V _{GS} =-10V | - | 46 | | nC |
| Gate-Source Charge | Qgs | | - | 16 | | nC |
| Gate-Drain Charge | Qgd | | - | 24 | | nC |
| Diode Forward Voltage (Note 3) | Vsp | V _{GS} =0V,I _S =-20A | - | | -1.2 | V |
| Diode Forward Current (Note 2) | ls | | - | - | -65 | Α |
| Reverse Recovery Time | trr | TJ = 25°C, I_F =-20A di/dt = -100A/ μ s ^(Note3) | - | 49 | | nS |
| Reverse Recovery Charge | Qrr | | - | 71 | | nC |
| Forward Turn-On Time | ton | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD) | | | | |

Notes:

- $\textbf{1.} \ \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature}.$
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- $\textbf{5.} \ E_{AS} \ condition: \ Tj=25 \ ^{\circ}\text{C}, V_{DD}=-30 \ V, V_{G}=-10 \ V, L=0.5 \ mH, Rg=25 \Omega Typical \ Electrical \ and \ Thermal \ Characteristics \ (Curves)$





O 0.8 0 25 50 75 100 125 150 175 200 T_J-Junction Temperature(°C) Figure 4 Rdson-Junction Temperature Vgs Gate-Source Voltage (V) V_{DS}=-30V I_D=-20A 8 0 20 30 50 0 10 40 60 70 80 90 Qg Gate Charge (nC) Figure 5 Gate Charge 1.0E+02 1.0E+01 1.0E+00 1.0E-01 125°C

1.0E+02 (Y) 1.0E+01 1.0E+00 1.0E-01 1.0E-02 1.0E-03 1.0E-03 1.0E-04 25°C 25°C 25°C Vsd Source-Drain Voltage (V)

Figure 6 Source-Drain Diode Forward



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T_J-Junction Temperature(°C)

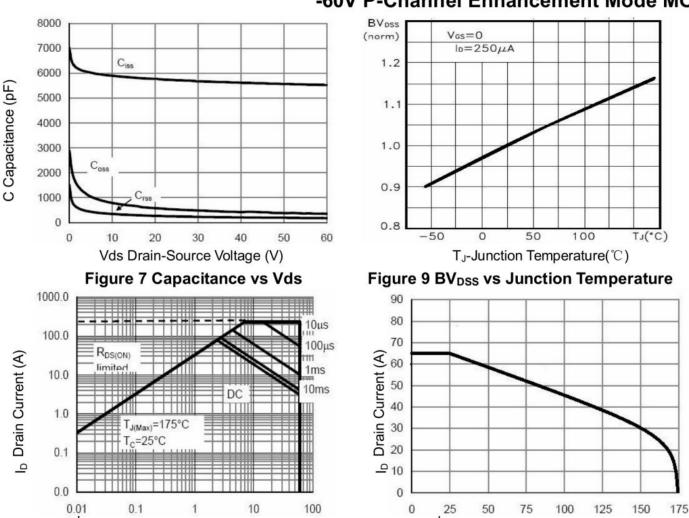


Figure 8 Safe Operation Area Figure 10 ID Current Derating vs Junction Temperature

Vds Drain-Source Voltage (V)

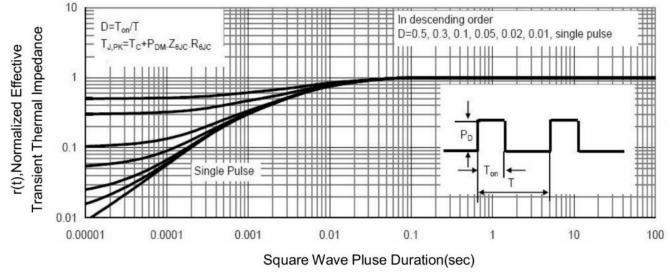
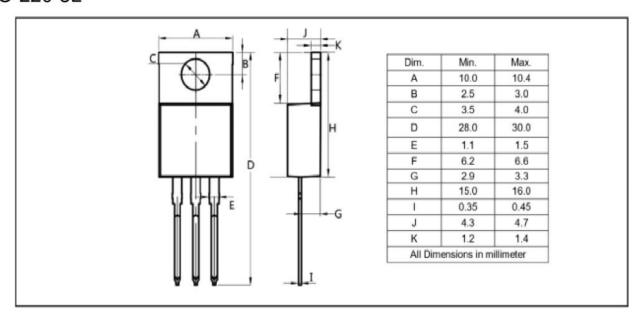


Figure 11 Normalized Maximum Transient Thermal Impedance



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TO-220-3L





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